

Title (en)  
COMPOSITION TO BE USED IN THE RESIN INJECTION MOULDING TECHNIQUE, CONTAINING LOW MOLECULAR WEIGHT COMPOUNDS JOINTLY FORMING A HYBRID NETWORK.

Title (de)  
NIEDRIGMOLEKULARE VERBINDUNGEN, DIE GEMEINSAM EIN HYBRIDES NETZWERK BILDEN, ENTHALTENDE, IN DER SPRITZGIESSTECHNIK VERWENDBARE ZUSAMMENSETZUNG.

Title (fr)  
COMPOSITION DEVANT S'UTILISER LORS DU MOULAGE PAR INJECTION DE RESINE ET CONTENANT DES COMPOSES A FAIBLE POIDS MOLECULAIRE FORMANT CONJOINTEMENT UN RESEAU HYBRIDE.

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Application  
**EP 91910509 A 19910521**

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Abstract (en)  
[origin: WO9118033A1] The invention relates to a composition to be used in the Resin Injection Moulding technique, which composition substantially contains low molecular weight compounds capable of forming a hybrid network, which composition at least contains a first component consisting of a compound with at least an ethylenic unsaturation and an isocyanate-reactive group, and a second component containing an ethylenically unsaturated monomer capable of copolymerizing with the first component, and a third component, which is a polyisocyanate, which composition is a composition of monomers with a molecular weight lower than 1000, the first component of which substantially consists of a monomer with substantially one terminal vinyl group per molecule and further substantially one isocyanate-reactive group per molecule and has a molecular weight lower than 500.

IPC 1-7  
**C08G 18/67**; **C08F 299/06**

IPC 8 full level  
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